

## SiC Bridge Rectifier

#### SKM125KD12SC

#### Features\*

- Full Silicon Carbide (SiC) power module
- 1200V SiC Schottky FWDs
- High frequency rectifier
- Improved thermal performances with Aluminium Nitride (AIN) substrate
- UL recognized, file no. E63532

#### **Typical Applications**

- Rectifiers for DC/DC converters
- High frequency rectifier applications

#### **Remarks**

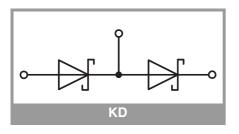
- Case temperature limited to  $T_C=125^{\circ}C$
- Recommended T<sub>jop</sub>= -40...+150°C

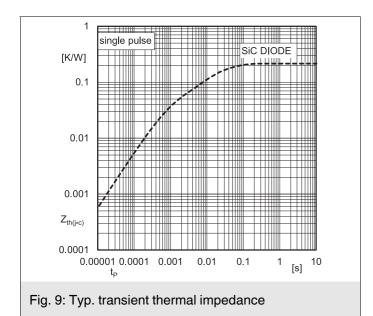
Absolute Maximum Ratings						
Symbol	Conditions		Values	Unit		
Diode 1	·					
$V_{RRM}$	T <sub>j</sub> = 25 °C		1200	V		
I <sub>F</sub>	T <sub>j</sub> = 175 °C	T <sub>c</sub> = 25 °C T <sub>c</sub> = 80 °C	264	Α		
		T <sub>c</sub> = 80 °C	200	Α		
I <sub>Fnom</sub>			180	Α		
I <sub>FSM</sub>	10 ms, sin 180°, T <sub>j</sub> = 150 °C		630	Α		
i <sup>2</sup> t	10 ms, sin 180°, T <sub>j</sub> = 150 °C		1984	A <sup>2</sup> s		
T <sub>j</sub>			-40 175	°C		

Absolute Maximum Ratings					
Symbol	Conditions	Values	Unit		
Module					
I <sub>t(RMS)</sub>		500	Α		
T <sub>stg</sub>	module without TIM	-40 125	°C		
V <sub>isol</sub>	AC sinus 50 Hz, t = 1 min	4000	٧		

Characteristics							
Symbol	Conditions	min.	typ.	max.	Unit		
Diode 1	•					•	
$V_{F}$	I <sub>F</sub> = 180 A	T <sub>j</sub> = 25 °C		1.36	1.55	V	
	chiplevel	T <sub>j</sub> = 150 °C		1.70	1.98	V	
V <sub>F0</sub>	chiplevel	T <sub>j</sub> = 25 °C		0.95	1.05	V	
		T <sub>j</sub> = 150 °C		0.80	0.90	V	
r <sub>F</sub>	chiplevel	T <sub>j</sub> = 25 °C		2.3	2.8	mΩ	
		T <sub>j</sub> = 150 °C		5.0	6.0	mΩ	
C <sub>j</sub>	V <sub>R</sub> = 800 V, f = 1 MHz, T <sub>j</sub> = 25 °C			0.840		nF	
Qc	$V_R = 800 \text{ V, di/dt}_{off} = 500 \text{ A/}\mu\text{s,}$ $T_j = 25 ^{\circ}\text{C}$			0.67		μС	
R <sub>th(j-c)</sub>	per diode				0.215	K/W	

Characteristics							
Symbol	Conditions	min.	typ.	max.	Unit		
Module						•	
L <sub>CE</sub>				15		nΗ	
R <sub>CC'+EE'</sub>	measured per switch	T <sub>C</sub> = 25 °C		0.55		mΩ	
		T <sub>C</sub> = 125 °C		0.85		mΩ	
R <sub>th(c-s)</sub>	calculated without thermal coupling (λ <sub>grease</sub> =0.81 W/(m*K))			0.02	0.038	K/W	
Ms	to heat sink M6		3		5	Nm	
Mt		to terminals M6	2.5		5	Nm	
	1					Nm	
W		-			325	g	





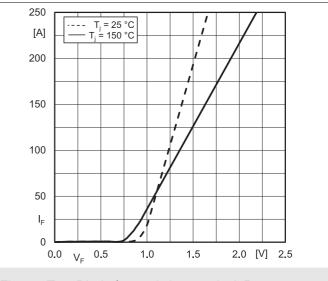


Fig. 10: Typ. Diode forward charact., incl.  $R_{\text{CC'+} \text{EE'}}$ 

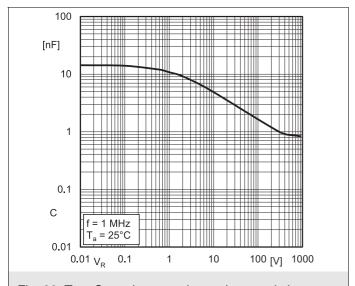
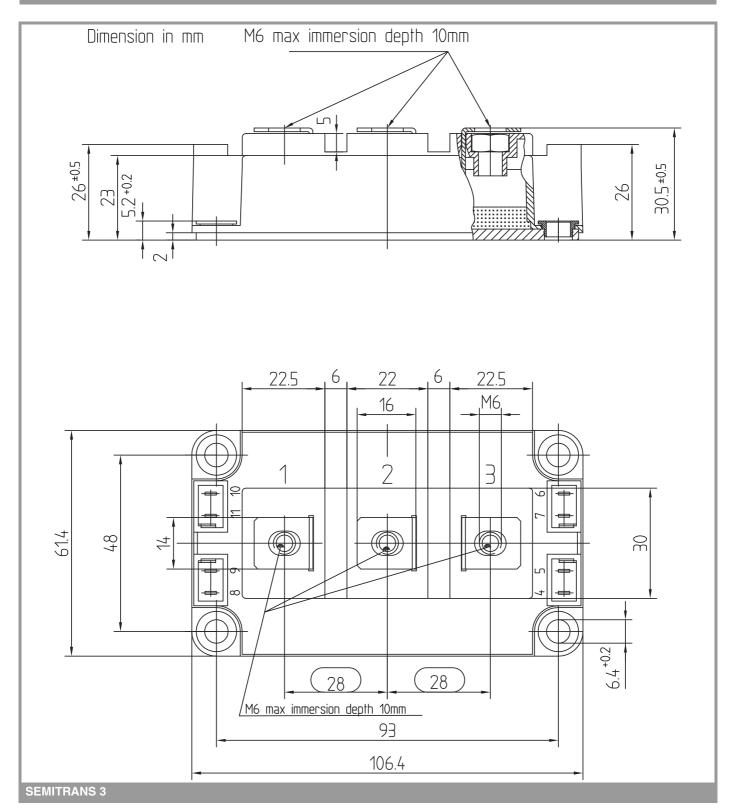
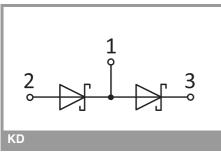


Fig. 20: Typ. Capacitance-voltage characteristic





This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

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